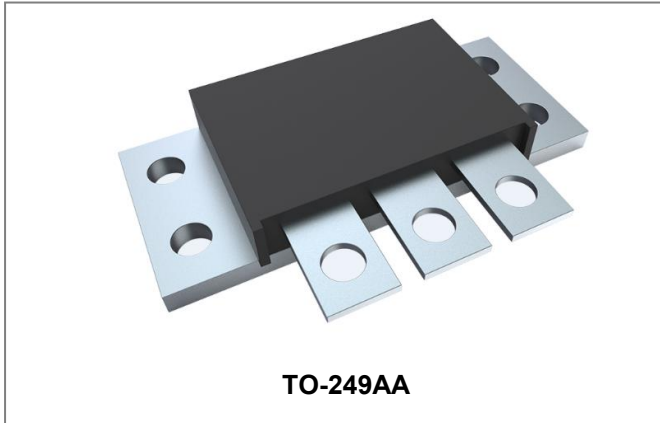


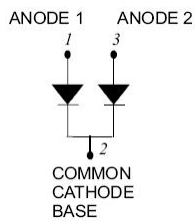
## 166CMQ200 SCHOTTKY RECTIFIER



### Features

- 175°C T<sub>J</sub> operation
- Isolated heatsink
- Low profile, high current package
- Center tap module
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Schematic & Pin Configuration



### Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

### Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	-	200	V
Average Rectified Forward Current	I <sub>F (AV)</sub>	50% duty cycle @T <sub>C</sub> =87°C, rectangular wave form	80(Per Leg) 160(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current	I <sub>FSM</sub>	8.3 ms, half Sine pulse	960	A

**Electrical Characteristics:**

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(Peg Leg)*	V <sub>F1</sub>	@ 80A, Pulse, T <sub>J</sub> = 25 °C	0.90	1.10	V
	V <sub>F2</sub>	@ 80A, Pulse, T <sub>J</sub> = 75 °C	-	0.90	V
Reverse Current(Peg Leg)*	I <sub>R1</sub>	@V <sub>R</sub> = rated V <sub>R</sub> , T <sub>J</sub> = 25 °C	0.0002	1.5	mA
	I <sub>R2</sub>	@V <sub>R</sub> = rated V <sub>R</sub> , T <sub>J</sub> = 125 °C	0.3	21	mA
Junction Capacitance(Peg Leg)	C <sub>T</sub>	@V <sub>R</sub> = 5V, T <sub>C</sub> = 25 °C f <sub>SIG</sub> = 1MHz	750	900	pF
Voltage Rate of Change	dv/dt	-	-	10,000	V/μs

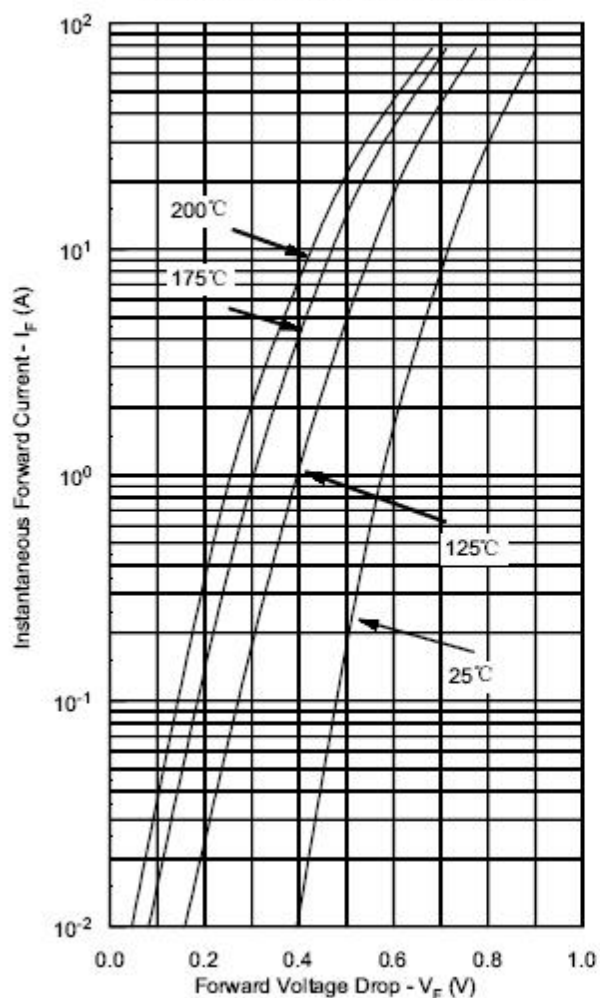
\* Pulse width < 300 μs, duty cycle < 2%

**Thermal-Mechanical Specifications:**

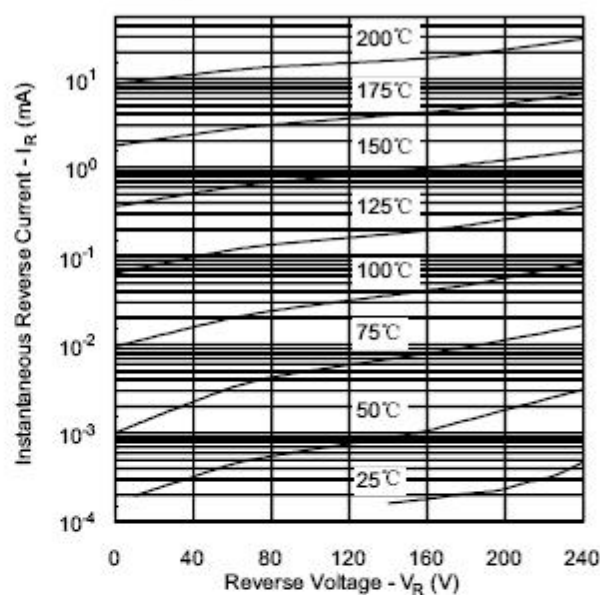
Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T <sub>J</sub>	-	-55 to +175	°C
Storage Temperature	T <sub>stg</sub>	-	-55 to +175	°C
Typical Thermal Resistance Junction to Case (Per Leg)	R <sub>θJC</sub>	DC operation	1	°C/W
Typical Thermal Resistance Junction to Case (Per Package)	R <sub>θJC</sub>	DC operation	0.5	°C/W
Typical Thermal Resistance, case to Heat Sink	R <sub>θcs</sub>	Mounting surface, smooth and greased	0.10	°C/W
Mounting Torque	T <sub>M</sub>	-	40(min)	Kg-cm
			58(max)	
Approximate Weight	wt	-	58	g
Case Style	TO-249(9 pin)			

**Ratings and Characteristics Curves**

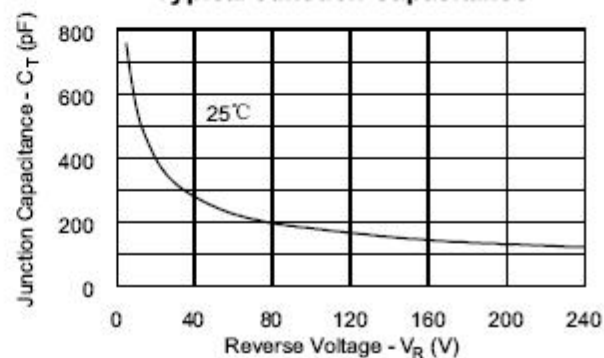
**Typical Forward Characteristics**



**Typical Reverse Characteristics**



**Typical Junction Capacitance**

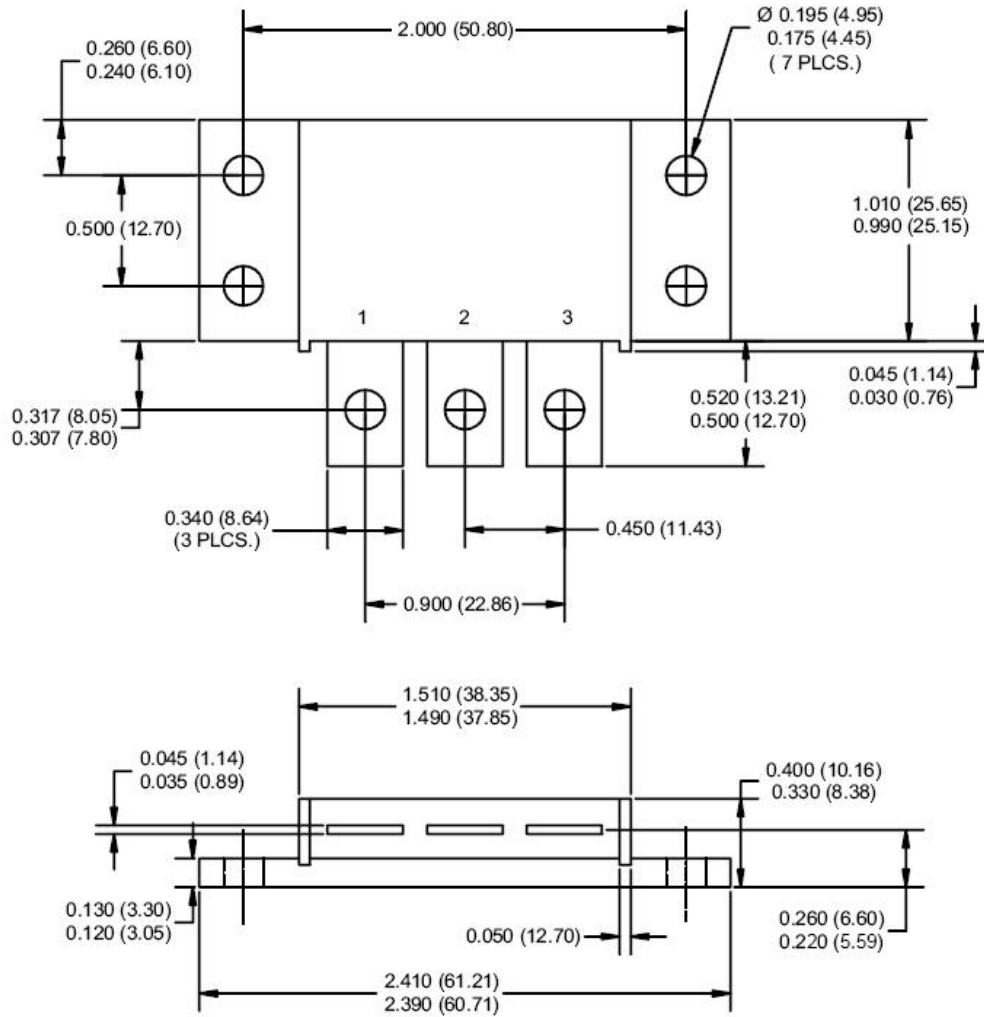


**Ordering Information**

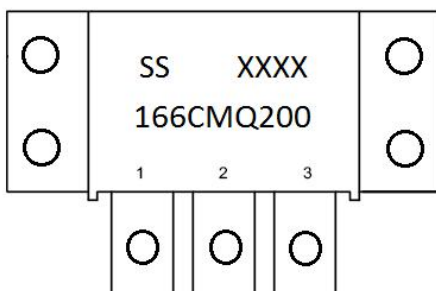
Device	Package	Shipping
166CMQ200	TO-249AA(Pb-Free)	24pcs/ box

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Mechanical Dimensions TO-249AA (Inches/Millimeters)**



**Marking Diagram**



Where XXXX is YYWW

1st row SS YYWW  
2nd row 166CMQ200  
3rd row 1 2 3 (pin)  
SS = SS  
YY = Year  
WW = Week

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

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